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| ENGINEERING | PRODUCT SPECIFICATION | SPEC.NO.: SPCH091A |
| DEPT. | For 2.54x2.54 mm (.100"x.100") Board to Board Connectors of System CH88 | PAGE: 1/3 |

1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

| | |
|-----------------|---|
| MIL - STD - 202 | Methods for test of connectors for electronic equipment |
| EIA 364 | Test methods for electrical connectors |
| J-STD-020 | Resistance to soldering Temperature for through hole Mounted Devices |
| SS-00254 | Test methods for electronic components ,LEAD-FREE soldering Part design standards |

3. APPLICABLE SERIES NO.: CH88***A100-B / CH88***B100-B
CH88***C100-B / CH88***D100-B

4. SHAPE,CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

0.8 mm (.031") ~ 1.6 mm (.063")



REVIEWED : Eisley APPROVED : Sun VERIFIED : Sandy .



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7. ELECTRICAL PERFORMANCE:

| | ITEM | TEST CONDITION | REQUIREMENT |
|-----|---------------------------|---|---------------------|
| 7.1 | Rated current and voltage | | 3A 250V AC (r.m.s.) |
| 7.2 | Contact resistance | Dry circuit of DC 20 mV max. 100 mA max. | Less than 20 mΩ |
| 7.3 | Dielectric strength | When applied AC 1000 V 1 minute between adjacent terminal | No change |
| 7.4 | Insulation resistance | When applied DC 500 V between adjacent terminal or ground | More than 5000 MΩ |

8. MECHANICAL PERFORMANCE:

| | ITEM | TEST CONDITION | REQUIREMENT |
|-----|---------------------|---|-----------------|
| 8.1 | Pin retention force | Apply axial pull out force at 25 ± 3mm/min on the assembly in the housing | More than 1 Kgf |

9. ENVIRONMENTAL PERFORMANCE:

| | ITEM | TEST CONDITION | REQUIREMENT |
|-----|---------------------|--|--|
| 9.1 | Cold Resistance | -40 °C ± 3 °C, 96 hours | Appearance: No damage Contact resistance: Δ20 mΩ change |
| 9.2 | Heat Resistance | 105 °C ± 3 °C, 96 hours | Appearance: No damage Contact resistance: Δ20 mΩ change |
| 9.3 | Temperature Cycling | 5 cycles (1) -40 °C , 30 min. (2) Room temp. 10-15 min. (3) 105 °C , 30 min. (4) Room temp. 10-15 min. | Appearance: No damage Contact resistance: Δ20 mΩ change |
| 9.4 | Humidity | 40±2 °C , 90-95% RH, 96 hours Measurement must be taken within 30 min. After tested | Appearance: No damage Contact resistance: Less than twice of initial |



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| | ITEM | TEST CONDITION | REQUIREMENT |
|-----|------------------------------|--|--|
| 9.4 | Salt Spray | Temperature: $35 \pm 2^{\circ}\text{C}$ Solution: $5 \pm 1\%$ Spray time: 6 ± 1 hours Measurement must be taken after water rinse | Appearance: No damage Contact resistance: $\Delta 20 \text{ m}\Omega$ max out. |
| 9.5 | Solder ability | Soldering time: 3 ± 0.5 sec Soldering pot: $230 \pm 5^{\circ}\text{C}$ | Minimum: 90% of immersed area |
| 9.6 | Resistance to soldering heat | Soldering time: 5 ± 0.5 sec Soldering pot: $260 \pm 5^{\circ}\text{C}$ | No damage |

10. OPERATING TEMPERATURE : -40°C to $+105^{\circ}\text{C}$